

## **Additional Assembly Site**

### **DiskOnChip Millennium Plus 9x12 FBGA 32MByte**

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#### **Description**

The AMKOR Japan fab assembly facility has been selected as an additional assembly facility for DiskOnChip Millennium Plus, manufactured by Toshiba. Until now, DiskOnChip Millennium Plus has been assembled at the Yokkaichi Toshiba Electronics (YTE) facility in Japan only. Starting in April 2004, DiskOnChip Millennium Plus will be assembled either at AMKOR or YTE in Japan.

There is no other change in the DiskOnChip Millennium Plus manufacturing and testing process. Wafers will continue to be manufactured at YTE, and testing will be done at Power Tech Technology (PTI).

#### **Ordering Information**

The following product is affected:

<b>Product</b>	<b>Form Factors</b>	<b>Capacity (MB)</b>	<b>Ordering Information</b>
DiskOnChip Millennium Plus	9x12 FBGA	32MByte/256Mbit	MD3831-D32-V3-X MD3831-D32-V3-X-P

#### **Reason for Change**

A new assembly site is being added to address the growing market demand. This step will provide additional flexibility and enable M-Systems to respond to customer needs.

#### **Timetable**

Products will be assembled at the AMKOR site according to the following schedule:

<b>Product</b>	<b>Ordering Information</b>	<b>Schedule</b>
DiskOnChip Millennium Plus 32MByte/256Mbit	MD3831-D32-V3-X	April 2004
DiskOnChip Millennium Plus 32MByte/256Mbit, Pb-free	MD3831-D32-V3-X-P	

Note: Samples will be available as of March 2004

#### **Compatibility**

The products assembled in the new facility are fully hardware and software compatible with the existing products.

### **Quality Assurance Procedure**

Overall responsibility for quality assurance and quality control procedures will remain under the auspices of YTE in Japan. M-Systems and Toshiba are working closely to ensure a smooth addition of the alternative assembly facility. The following actions will be implemented:

- Correlation testing between products that have been assembled at different sites (YTE and AMKOR).
- Functional testing by both M-Systems and Toshiba
- Long-term reliability testing
- Extended monitoring of the first lots manufactured at the new assembly site

### **How to Contact Us**

Please contact your M-Systems representative or visit the DiskOnChip web page on the M-Systems website ([www.m-sys.com](http://www.m-sys.com)) for any further information or assistance.

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